50 Years of Pioneering Precision Technology: LPKF Laser & Electronics at electronica 2026

LPKF Laser & Electronics is celebrating its 50th anniversary in 2026 and will show at electronica 2026 how technological progress makes manufacturing processes more competitive.

The ProtoLaser H4 builds speed into the process. With laser-based, digitally supported iteration and CircuitPro software, development labs produce a complete 4-layer multilayer PCB, including plated vias, in-house in a single working day. Outsourcing the same board to external service providers takes days.

The new CuttingMaster 3290 combines speed with efficiency. It has 90 W of laser power, significantly more than its predecessor. Together with LPKF's Tensor Technology, it doubles throughput on FR4 substrates up to 2.4 mm thick, with stress-free cuts and maximum yield.

As a bridge partner, LaserMicronics gives customers immediate access to LPKF's UV, infrared and ultrashort pulse (USP) laser systems without investing in equipment of their own: customers pay for the result, not for machines or maintenance.

LPKF's ATA technology overcomes a technical limit that previously applied. It permanently joins two laser-absorbing plastic parts with a single laser. Until now, the process required one transparent and one absorbing part. This creates new design freedom for medical technology as well as for high-volume series production in the automotive and consumer electronics industries.

LPKF's LIDE technology, integrated into the NEXAR product line, creates defect-free through glass vias across the entire glass thickness range from 50 µm to 2 mm using the same process. This system consistency drives stable, reproducible processes for high-volume production of glass core substrates.

LPKF invites visitors to electronica 2026 to see its key product lines live: Hall A2, Booth 219, Messe München, November 10 to 13, 2026.